Final Product/Process Change Notification

Document #:FPCN23660XD
Issue Date:26 May 2022

Title of Change:	Additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu located in Aizu, Japan.
Proposed First Ship date:	31 Aug 2022 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or PetrCDC.Valek@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Labels on boxes and reels will show "Diffused In: JP" for product produced out of Aizu, Japan. There is no changes to the marking of the actual units. Material from (2) different FABs cannot be combined into one reel.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Aizu, Japan	None

Description and Purpose:

The company onsemi would like to inform its customers of additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu, Japan Manufacturing located in Aizu, Japan for the devices listed in this FPCN.

All products listed here will be dual sourced from its current wafer fab facility in onsemi wafer fab in Gresham, US and Aizu, Japan.

There is no change to the orderable part number.

There is no product marking change as a result of this change.

	Before Change Description	After Change Description
Wafer Fab Site	Gresham, US	Gresham, US and Aizu, Japan

Reliability Data Summary:

QV DEVICE NAME: NCP4306DADZZDASNT1G
RMS: S77062
PACKAGE: TSOP6

Test	Specification	Condition	Interval	Results (fail/pass)
HTOL	JESD22-A108	Ta=125°C, bias at Vcc= 1.2X Nominal (not to exceed Max rated)	1008hrs	0/240
HTSL	JESD22-A103	Ta = 150°C	1008hrs	0/240
TC+PC	JESD22-A104	Temp = -65°C to +150°C	500 cycles	0/240
UHAST+PC	JESD22-A118	Temp = 130°C, RH=85%, ~ 18.8 psig	96hrs	0/240
SAT	as outlined in MSB17722C	12MSB17722C		0/30

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
NCP4306DADZZDASNT1G	NCP4306DADZZDASNT1G
NCP4306DADZZBASNT1G	NCP4306DADZZDASNT1G
NCP4306DAHZZAASNT1G	NCP4306DADZZDASNT1G